

January 2009

FDP8440

N-Channel PowerTrench® MOSFET

40V, 277A, 2.2mΩ

Features

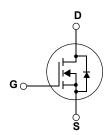
- $R_{DS(on)} = 1.64 \text{m}\Omega \text{ (Typ.)} \otimes V_{GS} = 10 \text{V, } I_D = 80 \text{A}$
- $Q_{g(tot)} = 345nC (Typ.)@V_{GS} = 10V$
- Low Miller Charge
- Low Q_{RR} Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- · RoHS Compliant



Application

- · Automotive Engine Control
- · Powertrain Management
- · Motors, Solenoids
- · Electronic Steering
- · Integrated Starter/ Alternator
- Distributed Power Architectures and VRMs
- · Primary Switch for 12V Systems





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol		Ratings	Units	
V _{DSS}	Drain to Source Voltage	Drain to Source Voltage		
V _{GSS}	Gate to Source Voltage		±20	V
I _D	Drain Current	- Continuous (T _C = 25°C, Silicon Limited) - Continuous (T _C = 100°C, Silicon Limited) - Continuous (T _C = 25°C, Package Limited)	277* 196* 100	А
I _{DM}	Drain Current	- Pulsed (Note 1)	500	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		1682	mJ
P _D	Dawar Dissipation	$(T_C = 25^{\circ}C)$	306	W
	Power Dissipation	- Derate above 25°C	2.04	W/°C
T _{J,} T _{STG}	Operating and Storage	-55 to +175	οС	
TL	Maximum Lead Tempera 1/8" from Case for 5 Sec	300	°C	

^{*}Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 100A.

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.49	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Sink (Typ.)	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP8440	FDP8440	TO-220	N/A	N/A	50units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Conditions		Min	Тур	Max	Units
Off Charac	teristics	-			•	II.	•
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$		40			V
		V _{DS} = 32V				1	μА
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} = 0V	T _C = 150°C			250	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20V	•			±100	nA
On Charac	teristics	·					
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1		3	V
		V _{GS} = 4.5V, I _D = 80A		1.88	2.4		
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 80A				2.2	mΩ
		$V_{GS} = 10V, I_D = 80A,$ $T_C = 175^{\circ}C$				4.4	. 11152
Dynamic C	Characteristics	·					
C _{iss}	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz			18600	24740	pF
C _{oss}	Output Capacitance				1840	2450	pF
C _{rss}	Reverse Transfer Capacitance				1400	2100	pF
R _G	Gate Resistance	V _{GS} = 0.5V, f = 1MHz			1.1		Ω
Q _{g(tot)}	Total Gate Charge at 10V	V _{GS} = 0V to 10V			345	450	nC
Q _{g(2)}	Threshold Gate Charge	V _{GS} = 0V to 2V	$V_{DD} = 20V$		32.5		nC
Q _{gs}	Gate to Source Gate Charge		I _D = 80A		49		nC
Q _{gs2}	Gate Charge Threshold to Plateau		$I_g = 1.0 \text{mA}$		16.5		nC
Q _{gd}	Gate to Drain "Miller" Charge	7			74		nC
Switching	Characteristics (V _{GS} = 10V)						
t _{ON}	Turn-On Time				175	360	ns
t _{d(on)}	Turn-On Delay Time	7/ - 20// - 204			43	95	ns
t _r	Rise Time	$V_{DD} = 20V, I_{D} = 80A$ $V_{GS} = 10V, R_{GEN} = 7\Omega$			130	275	ns
t _{d(off)}	Turn-Off Delay Time	VGS 10V, NGEN 732			435	875	ns
t _f	Fall Time				290	590	ns
t _{OFF}	Turn-Off Time				730	1470	ns
Drain-Sour	rce Diode Characteristics and Maximu	m Ratings					
V	Source to Drain Diode Voltege	I _{SD} = 80A				1.25	V
V_{SD}	Source to Drain Diode Voltage	I _{SD} = 40A				1.0	V
t _{rr}	Reverse Recovery Time	$I_{SD} = 75A$, $dI_{SD}/dt = 100$	0A/μs		59		ns
Q _{RR}	Reverse Recovery Charge	$I_{SD} = 75A$, $dI_{SD}/dt = 100$	0Α/μs		77		nC

NOTES

^{1:} Pulse width limited by maximum junction temperature.

^{2:} Starting T $_{J}$ = 25°C, L = 1mH, I $_{AS}$ = 58A, V $_{DD}$ = 36V, V $_{GS}$ = 10V.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

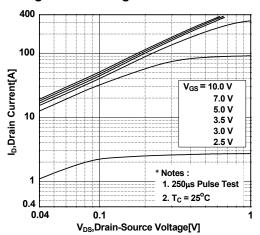


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

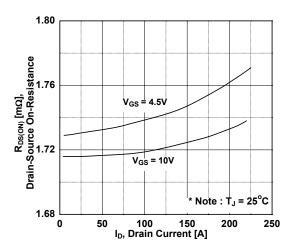


Figure 5. Capacitance Characteristics

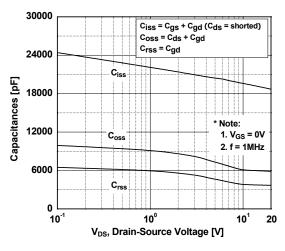


Figure 2. Transfer Characteristics

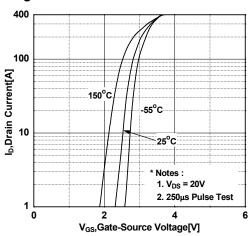


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

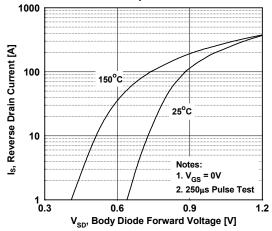
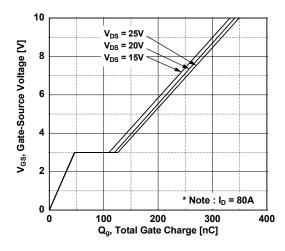


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

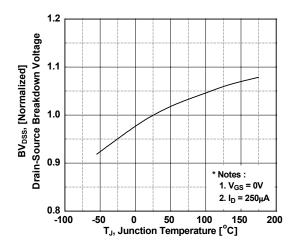


Figure 9. Unclamped Inductive Switching Capability

Figure 8. On-Resistance Variation vs. Temperature

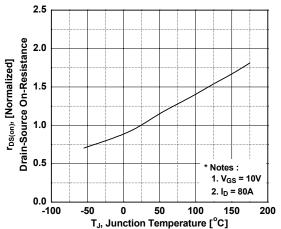
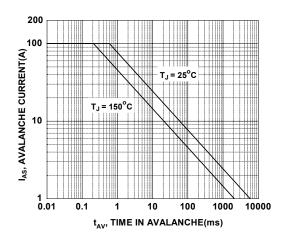


Figure 10. Safe Operating Area



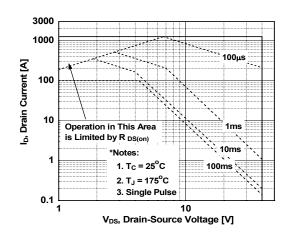
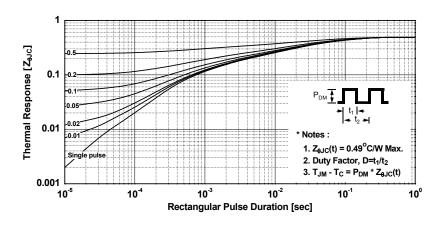
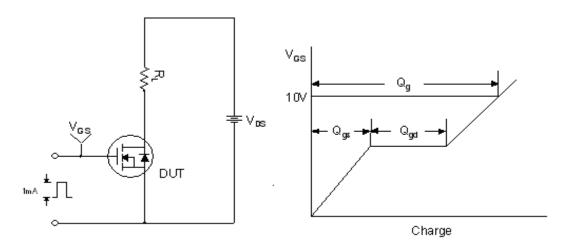


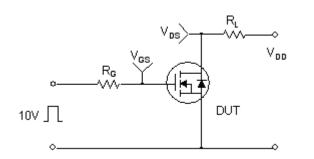
Figure 11. Transient Thermal Response Curve

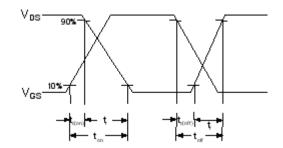


Gate Charge Test Circuit & Waveform

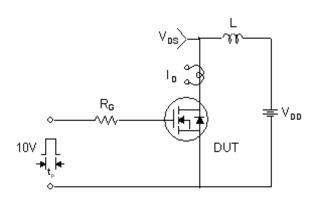


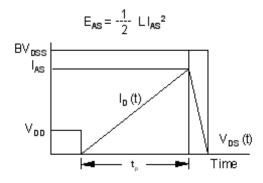
Resistive Switching Test Circuit & Waveforms



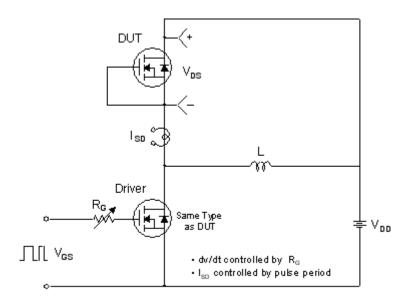


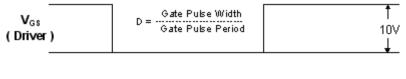
Unclamped Inductive Switching Test Circuit & Waveforms

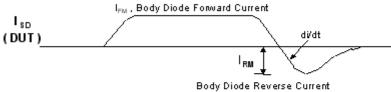


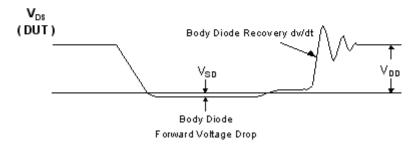


Peak Diode Recovery dv/dt Test Circuit & Waveforms



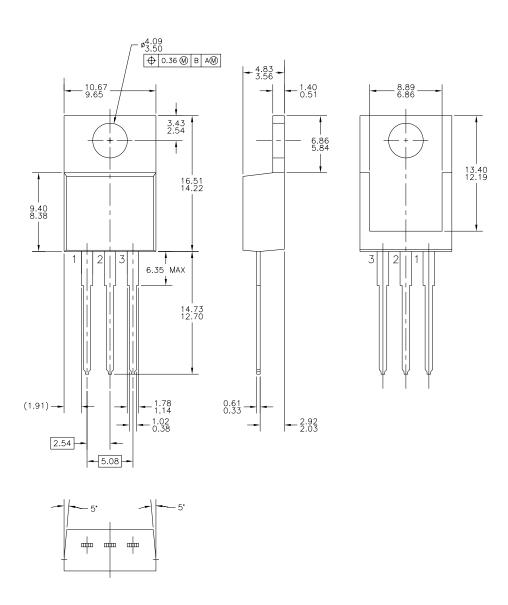






Mechanical Dimensions

TO-220







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